



## INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

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| (54) Title: WATER-BASED RESIN COMPOSITION                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                     |  |                                                                                                                           |                                                                                                                                    |
| (57) Abstract                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                 |  |                                                                                                                           |                                                                                                                                    |
| <p>A thermosetting water-based resin composition comprising an oil-soluble initiator of which a temperature for one-minute half-life is from 90° to 270 °C and a polycondensation resin comprising an unsaturated dicarboxylic acid having a radical-polymerizable unsaturated bond or an acid anhydride thereof as at least one constituent monomer, wherein the polycondensation resin has an acid value of from 3 to 100 mg KOH/g, and wherein said oil-soluble initiator is present in said polycondensation resin; a process for preparing the thermosetting water-based resin composition; a molding compound composition comprising the water-based resin composition; and a molding product prepared by molding the molding compound composition.</p> |  |                                                                                                                           |                                                                                                                                    |